L Number	Hits	Search Text	DB	Time stamp
1	2	6490368.pn.	USPAT;	2003/09/05 11:33
			US-PGPUB;	
		•	EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
6	· 10	382/147	US-PGPUB	2003/09/05 11:42
-	2	4926452.pn.	USPAT;	2003/09/05 11:33
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	_		IBM_TDB	
-	. 2	5081656.pn.	USPAT;	2003/08/30 23:20
			US-PGPUB;	
		'	EPO; JPO;	
			DERWENT;	
		5007400	IBM_TDB	
-	2	5097492.pn.	USPAT;	2003/08/30 23:20
			US-PGPUB;	
	,		EPO; JPO;	
			DERWENT;	
	_	5400054	IBM_TDB	0000/00/00 00 0
-	2	5199054.pn.	USPAT;	2003/08/30 23:21
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
	•	5050040	IBM_TDB	0000/00/00 00 00
-	, 2	5259012.pn.	USPAT;	2003/08/30 23:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	2	5201525 mm	IBM_TDB	0000/00/00 00 00
-	2	5291535.pn.	USPAT;	2003/08/30 23:22
			US-PGPUB;	
ŀ			EPO; JPO;	
			DERWENT;	
	2	5561696.pn.	IBM_TDB	2003/08/30 23:23
-	2	556 1696.pm.	USPAT; US-PGPUB;	2003/06/30 23:23
			EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
_	2	5583904.pn.	USPAT;	2003/08/30 23:24
	-	- 0000004.рп.	US-PGPUB;	2003/00/30 23.24
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	2	5621811.pn.	USPAT;	2003/08/30 23:41
}	_		US-PGPUB;	2000/00/30 20.41
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
	2	5687209.pn.	USPAT;	2003/08/30 23:25
	-		US-PGPUB;	2000/00/00 20.20
	•		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
.	118	378/22.ccls.	USPAT;	2003/08/30 23:30
			US-PGPUB;	2300,00,00 20.00
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	216	382/147.ccls.	USPAT;	2003/08/30 23:30
	2.10		US-PGPUB;	2000/00/00 20.00
			EPO; JPO;	
			DERWENT;	

-	324	378/21.ccls.	USPAT;	2003/08/30 23:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1287	(identify\$3 or inspect\$3 or evaluat\$3) with solder\$3 with	USPAT;	2003/08/31 00:17
		(joint\$1 or connection\$1)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	21	((identify\$3 or inspect\$3 or evaluat\$3) with solder\$3 with	USPAT;	2003/09/05 11:42
	1	(joint\$1 or connection\$1)) and ((distance or space or gap) with	US-PGPUB;	
		(mount\$3 with surface\$1 with board))	EPO; JPO;	'
			DERWENT;	
			IBM_TDB	
-	65	((identify\$3 or inspect\$3 or evaluat\$3) with solder\$3 with	USPAT;	2003/08/31 00:07
		(joint\$1 or connection\$1)) and ((distance or space or gap) with	US-PGPUB;	
		(surface\$1 with board))	EPO; JPO;	`
			DERWENT;	
	_		IBM_TDB	0000/00/04 00:00
-	5	((identify\$3 or inspect\$3 or evaluat\$3) with solder\$3 with	USPAT;	2003/08/31 00:08
		(joint\$1 or connection\$1)) and (neighbor)	US-PGPUB;	
		·	EPO; JPO; DERWENT;	
			IBM_TDB	
	600	(/distance or anges or gon) with (mount\$3 with surface\$1 with	USPAT;	2003/08/31 00:17
-	683	((distance or space or gap) with (mount\$3 with surface\$1 with	US-PGPUB;	2003/00/31 00.17
		board) same (printed with circuit))	EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
	612	((distance or space) with (mount\$3 with surface\$1 with board)	USPAT;	2003/08/31 00:17
- :	012	same (printed with circuit))	US-PGPUB;	2000/00/01/00:11
		Same (printed with circuity)	EPO; JPO;	
			DERWENT;	_
			IBM_TDB	
_	10	(((distance or space or gap) with (mount\$3 with surface\$1	USPAT;	2003/08/31 00:27
		with board) same (printed with circuit))) and ((defect\$1 or	US-PGPUB;	
		quality) with solder\$3 with (joint\$1 or connection\$1))	EPO; JPO;	
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DERWENT;	
			IBM_TDB	
-	0	((identify\$3 or inspect\$3 or evaluat\$3) with solder\$3 with	USPAT;	2003/08/31 00:28
		(joint\$1 or connection\$1)) and (box adj plot)	US-PGPUB;	
			EPO; JPO;	
		·	DERWENT;	
		,	IBM_TDB	000000000000000000000000000000000000000
-	73	box adj plot	USPAT;	2003/08/31 00:28
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		(harradi alah) and (analy@4)	IBM_TDB USPAT;	2003/08/31 00:28
	64	(box adj plot) and (analy\$4)	US-PGPUB;	2003/00/31 00.20
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	1	((box adj plot) and (analy\$4)) and (solder)	USPAT;	2003/08/31 00:28
-	'	((box adj plot) and (analywy), and (solder)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		,	IBM_TDB	
_	185363	(chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or	USPAT;	2003/09/03 15:18
	.55555	modif\$4 or set\$4) with (threshold or criteria)	US-PGPUB;	
			EPO; JPO;	1
			DERWENT;	
		1 ,	IBM_TDB	1

-	33687	((chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or modif\$4 or set\$4) with (threshold or criteria)) and ((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:25
-	3	(((chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or modif\$4 or set\$4) with (threshold or criteria)) and ((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))) and (((printed adj circuit adj board) with solder with joint\$1) same ((location or position) with solder with (joint\$1 or connection\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:26
	. 1	((((chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or modif\$4 or set\$4) with (threshold or criteria)) and ((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))) and (((printed adj circuit adj board) with solder with joint\$1) same ((location or position) with solder with (joint\$1 or connection\$1)))) and ((distance or space) with mount\$3 with surface with board with device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:56
-	438825	((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:25
-	49	(((printed adj circuit adj board) with solder with joint\$1) same ((location or position) with solder with (joint\$1 or connection\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:53
-	380	((distance or space) with mount\$3 with surface with board with device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:27
-	1	((((printed adj circuit adj board) with solder with joint\$1) same ((location or position) with solder with (joint\$1 or connection\$1)))) and (((distance or space) with mount\$3 with surface with board with device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:27
-	92	(((printed adj circuit adj board) with solder with joint\$1) and ((location or position) with solder with (joint\$1 or connection\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:03
-	6	(((chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or modif\$4 or set\$4) with (threshold or criteria)) and ((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))) and ((((printed adj circuit adj board) with solder with joint\$1) and ((location or position) with solder with (joint\$1 or connection\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:56

				•
-	1	((((chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or modif\$4 or set\$4) with (threshold or criteria)) and ((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))) and ((((printed adj circuit adj board) with solder with joint\$1) and ((location or position) with solder with (joint\$1 or connection\$1))))) and ((distance or space) with mount\$3 with surface with board with device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:56
-	1514	((location or position) with solder with (joint\$1 or connection\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:03
-	239	((distance or space) with mount\$3 with surface with (circuit with board) with device\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/03 16:04
	. 1	((((chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or modif\$4 or set\$4) with (threshold or criteria)) and ((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))) and (((location or position) with solder with (joint\$1 or connection\$1)))) and (((distance or space) with mount\$3 with surface with	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:05
-	5	(circuit with board) with device\$1)) (((location or position) with solder with (joint\$1 or connection\$1))	USPAT; US-PGPUB;	2003/09/03 16:06
	21) and (((distance or space) with mount\$3 with surface with (circuit with board) with device\$1)) (((chang\$3 or adjust\$3 or adapt\$3 or calculat\$3 or alter\$3 or	EPO; JPO; DERWENT; IBM_TDB USPAT;	2003/09/04 11:53
-		modif\$4 or set\$4) with (threshold or criteria)) and ((defect\$3 or fault\$1 or error\$1 or quality) with (inspect\$3 or check\$3 or detect\$3 or test\$3 or examin\$5))) and (((location or position) with solder with (joint\$1 or connection\$1))	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/11.33
	1	((distance adj between) with (mounting adj surface) with device with (circuit adj board) with solder with (joint\$1 or connection\$1)) and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:36
-	1	((distance or space) with (mounting adj surface) with device with (circuit adj board) with solder with (joint\$1 or connection\$1)) and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:38
-	3	((distance or space) with (moun\$3 with surface) with device with (circuit adj board) with solder with (joint\$1 or connection\$1)) and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:39
-	8	((distance or space or gap) with surface with device with (circuit adj board)) and (solder with (joint\$1 or connection\$1))and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 16:17

			· · · · · · · · · · · · · · · · · · ·	
-	3	(((distance or space or gap) with surface with device with	USPAT;	2003/09/04 15:53
		(circuit adj board)) and (solder with (joint\$1 or	US-PGPUB;	
		connection\$1))and (location or position)	EPO; JPO;	
) and (threshold or criteria or range or limit)	DERWENT;	
			IBM_TDB	0000/00/04 45 50
-	1	((distance or space) with (mounting adj surface) with device	USPAT;	2003/09/04 15:53
		with (circuit adj board) with solder with (joint\$1 OR	US-PGPUB;	,
		connection\$1)) AND	EPO; JPO; DERWENT;	
		(location OR position)	IBM_TDB	
	84	((distance or space or gap) with surface with device with	USPAT;	2003/09/05 07:30
-	04	(circuit adj board)) and (solder with (joint\$1 or connection\$1))	US-PGPUB;	2003/03/03 07:30
		(Circuit adj board)) and (Soider with Jointon or connection 17))	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
 	1	RE35,423.pn.	USPAT:	2003/09/05 07:32
	'	11200, 120.4.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	
-	2	6,580,501.pn.	USPAT;	2003/09/05 07:31
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	5,780,866.pn.	USPAT;	2003/09/05 07:31
			US-PGPUB;	
		'	EPO; JPO;	
			DERWENT; IBM_TDB	
	2	4 702 692 nn	USPAT;	2003/09/05 07:31
-	2	4,792,683.pn.	US-PGPUB;	2003/03/03 07:31
		•	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	219	702/35.ccls.	USPAT;	2003/09/05 11:26
	-		US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	181	702/33.ccls.	USPAT;	2003/09/05 11:26
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	<u> </u>		IBM_TDB	